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# Components and Packaging for Laser Systems VI

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### Contents

- v Authors
- vii Conference Committee

#### **ADVANCED LASER PACKAGING SOLUTIONS**

- 11261 03 Ultrafast laser bonding of glasses and crystals to metals for epoxy-free optical instruments [11261-2]
- 11261 05 **3D-printed, low-cost, lightweight optomechanics for a compact, low-power solid-state amplifier system** [11261-4]
- 11261 06 Dielectric flat lens for the MIR region [11261-5]

#### LASER OPTICS AND OPTICAL ASSEMBLY

- 11261 07 Stable and robust optical assemblies for optical systems and lasers (Invited Paper) [11261-6]
- 11261 0A Automated sensor-guided packaging of diamond tools [11261-9]

#### LASER DIODE PACKAGING I

- High precision automated tab assembly with micro optics for optimized high-power diode laser collimation [11261-10]
- 11261 OC High power 250W CW conductively cooled diode laser arrays with low-smile [11261-11]

#### HIGH POWER/ENERGY LASER COMPONENTS AND PACKAGING

- 11261 OM Spectral dependence of the Verdet coefficients of terbium gallium garnet and potassium terbium fluoride [11261-21]
- 11261 0N Diode pumped passively Q-switched Nd:YAG/Cr:YAG solid-state lasers with a stable output of millijoules at 1064 nm over a wide temperature range [11261-22]
- 11261 00 High power thulium fiber laser systems for airborne and spaceborne missions [11261-23]

#### HIGH POWER/ENERGY LASER COMPONENTS I: BRAGG GRATINGS

- 11261 OPHigh performance FBG-based components for kilowatt fiber lasers power scaling<br/>(Invited Paper) [11261-24]
- 11261 OR Inner-cladding pump reflector based on chirped volume Bragg gratings [11261-26]

#### HIGH POWER/ENERGY LASER COMPONENTS II

- 11261 OT Anti-reflective meta-surfaces on optical fibers: an alternative to AR coatings (Invited Paper) [11261-29]
- 11261 0W Novel hollow-core chalcogenide fiber with anti-resonant arches for high-power infrared laser transmission [11261-32]

#### HIGH POWER/ENERGY LASER COMPONENTS III

- 11261 0Y Output laser coupler for coherent beam combining [11261-34]
- 11261 0Z Laser damage, a new US standard: What is in it for me? [11261-35]
- 11261 10 **An achromat singlet** [11261-36]

#### POSTER SESSION

11261 11	Narrow-linewidth, tunable external cavity diode lasers based on quantum-dot RSOA and Si_3N_4 microresonators in the hybrid platform $\left[11261\text{-}37\right]$
11261 13	Temperature distribution induced spectral broadening of high-power diode lasers [11261-39]
11261 14	High-strength high-efficiency cladding light strippers with CO <sub>2</sub> laser ablation [11261-40]
11261 15	Adjoint method and inverse design for diffractive beam splitters [11261-41]
11261 17	Development of a small RGB-laser light engine [11261-44]